

# Search Notes

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1574	(438/687).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/26 18:16
L2	2103	(438/656).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/26 18:16
L3	1263	(257/750).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/26 18:17
L4	1381	(257/751).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/26 18:17
L5	3411	(257/758).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/26 18:17
L6	71	tantalum adj nitride with barrier adj layer and damascene and copper near titanium	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/26 18:17
L7	4	cu and ti and titanium adj nitride same self-passivat\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/26 18:17
L8	29	dual adj damascene and cu with ti and tin and low-k and tan and passivation adj layer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/26 18:17
L9	55	copper with titanium same passivation with titanium near nitride	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/26 18:17

L10	64	copper same passivation with titanium near nitride	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/26 18:17
L11	5	self with passivation with titanium near nitride	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/26 18:17
S1	2	damascene and cu and ti and titanium adj nitride same self-passivat\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/08 02:41
S2	5	"6716753"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/08 02:41
S3	4	cu and ti and titanium adj nitride same self-passivat\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/26 18:17
S4	5	cu with ti and tin same self-passivat\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/08 03:06
S5	233	cu with ti and tin and low-k	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/08 03:06
S6	176	damascene and cu with ti and tin and low-k	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/08 03:06
S7	161	dual adj damascene and cu with ti and tin and low-k	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/08 03:06
S8	141	dual adj damascene and cu with ti and tin and low-k and tan	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/08 03:07

S9	23	dual adj damascene and cu with ti and tin and low-k and tan and passivation adj layer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/26 18:17
S10	22	dual adj damascene and cu with ti and tin and low-k and tan and passivation adj layer and barrier	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/08 03:19
S11	41	dual adj damascene and cu with ti and tin and low-k and tan and passivation and barrier	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/08 03:20
S12	5	dual adj damascene and cu near ti and tin and low-k and tan and passivation and barrier	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/08 03:21
S13	41	dual adj damascene and cu with ti and tin and low-k and tan and passivation and barrier	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/08 03:21
S14	38	dual adj damascene and cu with ti and tin and low-k and tan with barrier and passivation	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/08 03:21
S15	3	dual adj damascene and cu with ti and low-k and tan with barrier and passivation with tin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/17 23:59
S16	2	dual adj damascene and cu with ti and low-k and tan with barrier and self adj passivation with tin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/18 00:00
S17	1	"6472231".PN.	USPAT; USOCR	OR	ON	2004/11/18 00:00
S18	2	dual adj damascene and cu with ti and low-k and self adj passivation with tin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/18 00:01

S19	2	dual adj damascene and cu with ti and self adj passivation with tin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/18 00:01
S20	2	dual adj damascene and cu with ti and self adj passivation same tin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/18 00:01
S21	2	dual adj damascene and cu with ti and self with passivation same tin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/18 00:01
S22	2	damascene and cu with ti and self with passivation same titanium with nitride	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/18 00:02
S23	17	damascene and cu with ti and passivation same titanium with nitride	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/18 00:02
S24	10	damascene and cu with ti and passivation with titanium with nitride	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/18 00:02
S25	1334	(438/687).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/26 18:16
S26	2038	(438/656).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/26 18:16
S27	1175	(257/750).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/26 18:16
S28	1251	(257/751).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/26 18:17

S29	2957	(257/758).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/26 18:17
S30	961	(257/762).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/18 01:18
S31	9	"6387805"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/18 01:18
S32	3365	tantalum adj nitride with barrier	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/18 19:28
S33	769	tantalum adj nitride with barrier and damascene and copper with titanium	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/18 19:28
S34	86	tantalum adj nitride with barrier and damascene and copper near titanium	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/18 19:28
S35	54	tantalum adj nitride with barrier adj layer and damascene and copper near titanium	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/26 18:17
S36	2	tantalum adj nitride with barrier adj layer and damascene and copper near titanium and nitridation	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/18 19:29
S37	30	tantalum adj nitride with barrier adj layer and dual adj damascene and copper near titanium	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/18 19:30
S38	2	("6387805").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/18 22:56

S39	2	("6472231").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/18 22:56
S40	5	self with passivation with titanium near nitride	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/26 18:17
S41	283	passivation with titanium near nitride	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/09 22:27
S42	61	copper same passivation with titanium near nitride	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/26 18:17
S43	52	copper with titanium same passivation with titanium near nitride	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/26 18:17